



FH MONDAY

18 July 2016

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SoftBank to buy UK's Arm for £24.3bn

Japan's SoftBank has agreed to acquire Arm Holdings, the UK's pre-eminent technology company, for £24.3bn in an enormous bet by the Japanese telecoms group that the smartphone chip designer will make it a leader in one of the next big tech markets, the internet of things.

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ST Grows STM32 MCU Family

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IMEC, ARM Collaborate on 7nm Design

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Co-Robots Tend 3-D Printers

LAKE WALES, Fla. — Tend.ai claims to be the world's first artificially intelligent (AI) cooperative robot (co-robotic) tender of 3-D printers, in-circuit-testers (ICTs) for printed-circuit boards (PCBs), punch presses and other automated manufacturing devices. It now aims to bring manufacturing back to the U.S. by offering a cloud-based software automation system for users with no technical knowledge.

Using a web-cam attached to the robot's gripper and thin-client into which the user plugs all their devices, its AI software in the cloud manages the performance of all the tasks workers would have to perform manually. This includes configuring all devices, pushing their buttons, moving partly constructed devices from machine to machine, fetching the final manufactured parts and packaging them into boxes.

Rambus to Buy Inphi's Memory Business

SAN FRANCISCO—Chip and intellectual property vendor Rambus Inc. will acquire Inphi Corp.'s memory interconnect business for \$90 million in cash, the company said Thursday (June 30).

Rambus, which re-entered the fabless semiconductor market last year after years of doing business strictly as a technology licensor, said the deal would strengthen its position in the memory buffer chip market. The acquisition includes product inventory, customer contracts, supply chain agreements and IP, Rambus (San Jose, Calif.) said.

"By combining our buffer chip team with the memory interconnect business of Inphi, we are able to instantly gain a strong market position and be well situated for future growth," said Ron Black, Rambus president and CEO, in a statement.

Softbank To Buy UK's Arm For £24.3bn

Japan's SoftBank has agreed to acquire Arm Holdings, the UK's pre-eminent technology company, for £24.3bn in an enormous bet by the Japanese telecoms group that the smartphone chip designer will make it a leader in one of the next big tech markets, the internet of things.

The takeover of Cambridge-based Arm, which was founded 25 years ago and now employs 4,000 people, will be the largest acquisition of a European technology business. SoftBank will pay £17 in cash for each share in Arm, a 43 per cent premium to its closing price last week. Arm shares were trading at £16.99 in early London trading.

The deal, announced on Monday morning, comes just weeks after the UK elected to exit the EU, a decision that raised questions over the attractiveness of the country's business community. But Arm, as a global force in chip design, is better insulated from the vote for Brexit than many other UK companies by its leadership role in a key segment of the chip industry and the fact that it earns in US dollars.

ST Grows STM32 MCU Family

STMicroelectronics has introduced a development ecosystem for its latest low-power, high-performance STM32L4 microcontrollers (MCU) and expanded the series with five product lines comprising a range of package and memory-density options.

The expanded STM32L4 ecosystem builds on ST's free STM32Cube platform. This comprises the STM32CubeMX initialization-code generator and configurator with power estimation for ultra-low-power design, and the STM32CubeL4 package that contains middleware components, Nucleo-32 Board-Support Package (BSP), Hardware Abstraction Layer (HAL), and Low-Layer APIs (LLAPIs). For a quick start to new projects, the slim-form-factor NUCLEO-L432KC board – the first Nucleo-32 board to integrate an MCU in the tiny QFN32 package - includes an STM32L432KCU6 device (UFQFPN32) and provides direct access to ARM mbed online tools. Its Arduino Nano pin layout simplifies function extensions, and the integrated ST-Link debugger/programmer supports mass storage and allows probe-free debugging.

IMEC, ARM Collaborate On 7nm Design

LONDON--Processor intellectual property licensor ARM Holdings plc (Cambridge, England) has signed on to the INSITE collaborative research program on design at nanoelectronics research institute IMEC (Leuven, Belgium).

The INSITE program was started in 2009 and now has more than 10 participants with a focus on enabling design for chip process nodes at 7nm and beyond.

INSITE makes use of the knowledge gained in IMEC's lithography and logic device scaling programs to help companies anticipate design parameters and options for next-generation systems and applications. Developers are now faced by a large number of potential design choices at 7nm including: the required number of lithography exposures, device architecture such as FinFETs or lateral nanowires, the local interconnect scheme, cell architecture and the metallization scheme.